SPECIFICATION FOR APPROVAL

CUSTOMER.: **PART NO.:**

DESCRIPTION: LTA-5824-2G4H2-A1 **SAMPLE NO:**

DATE:

	FULLY APPROVED	PARTIALLY APPROVED	REJECTED
SIGN			
SUGGESTION			

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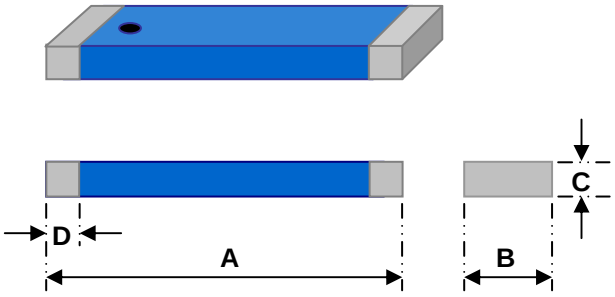
SPECIFICATION FOR APPROVAL

◆ PRODUCT DIMENSION



Dimensions			
A	**B**	**C**	**D**
5.8±0.2	2.4±0.2	0.9±0.2	0.4±0.2

NOTE ：Dimensions in mm

◆ PRODUCT IDENTIFICATION

L T A – 8 5 2 4 – # # # x x – G 0 1
① ② ③ ④

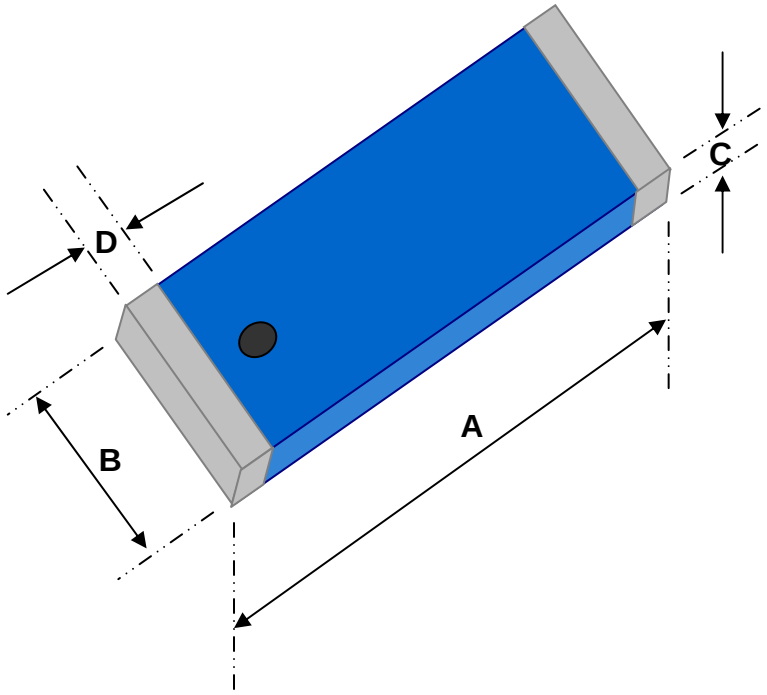
① Product Code
② Dimension Code
③ Series Type (# # # represents center frequency and x x represents material type)
④ Design Code

◆ TERMINAL CONFIGURATION

① Feed Termination
② Solder Termination

CUSTOMER:	CUSTOMER'S PART NO. / DWG NO.

ITEM/PART NO. : LTA-5824-2G4H2-A1



DIMENSION: (m/m)

A	5.8±0.2	m/m
B	2.4±0.2	m/m
C	0.9±0.2	m/m
D	0.4±0.20	m/m
E		m/m
F		m/m
G		m/m
H		m/m
I		m/m
J		m/m
K		m/m
L		m/m
M		m/m
N		m/m
O		m/m
P		m/m

ELECTRICAL REQUIREMENTS	
Center Frequency	2450 MHz
Bandwidth	~300 MHz
Gain	1~2 dBi
VSWR	2.0 max.
Polarization	Linear

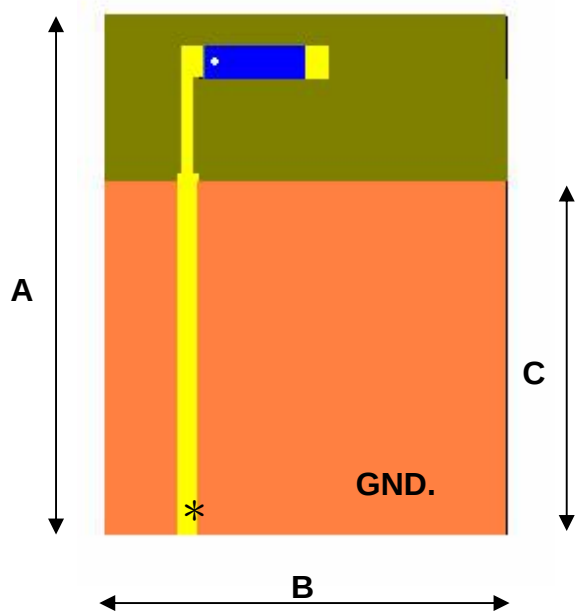
TEST INSTRUMENTS

HP 8753E NETWORK ANALYZER

DRAWN BY	CHECKED BY	APPROVED BY	SAMPLE NO.

ELECTRICAL CHAPACTERISTIC

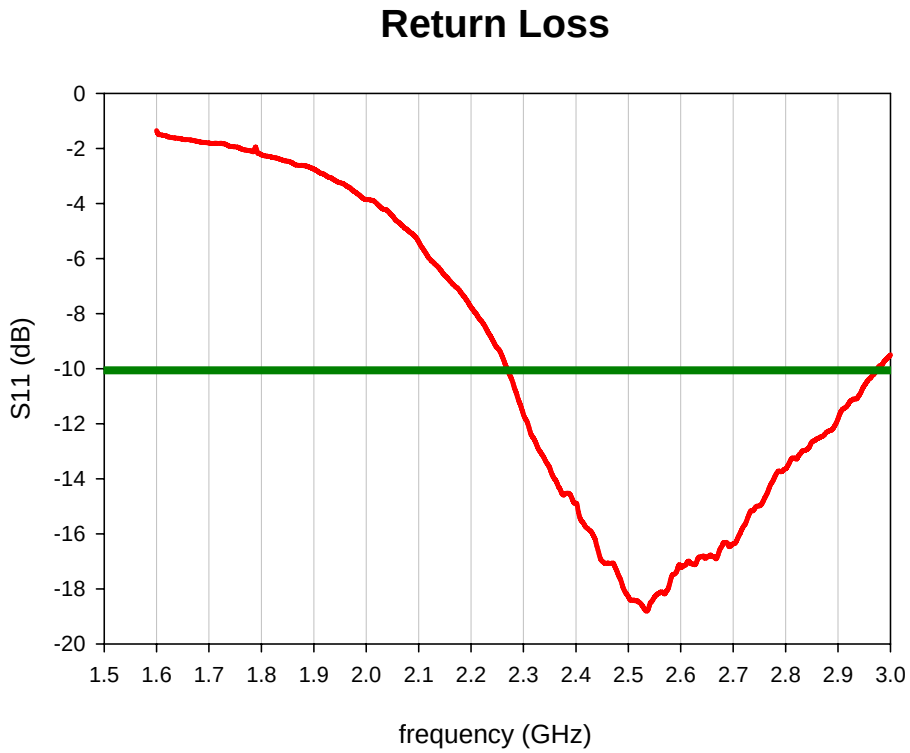
◆ TESTING BOARD



Dimensions		
A	**B**	**C**
40	30	28
* : 50 Ohm Transmission Line		

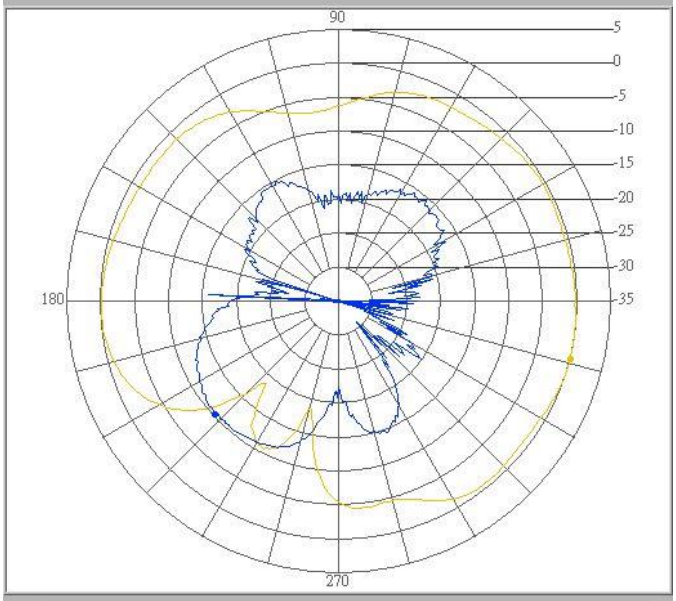
NOTE : Dimensions in mm

◆ RETURN LOSS



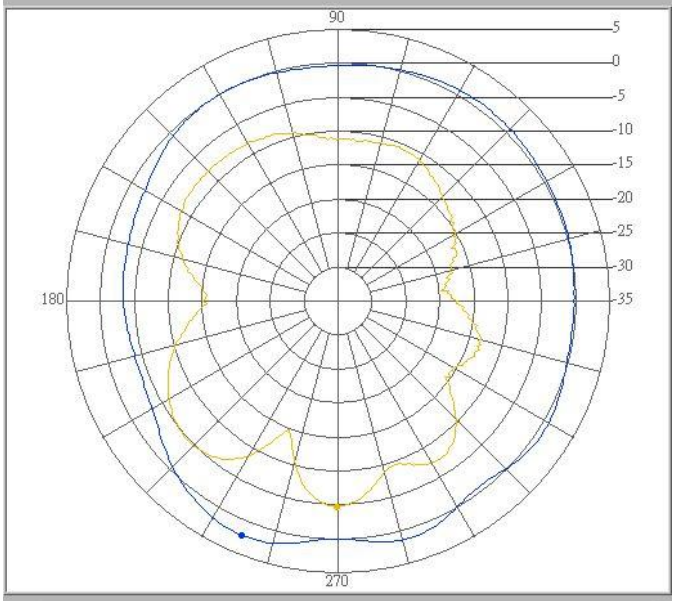
◆ RADIATION PATTERN

XY Plane Pattern



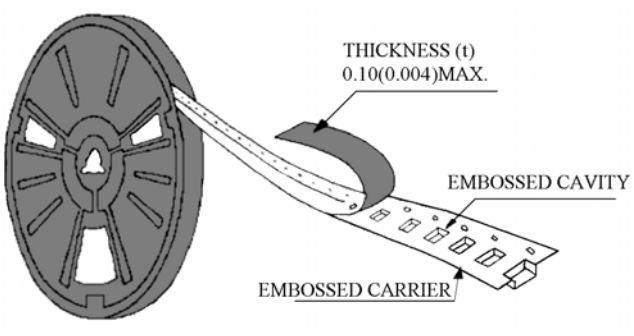
Model No.	Ant. Polarization	Freq(MHz)	Peak angle	Value	Average
美磊 Maglayer__XYplane--H	Horizontal	2480	346.0	0.1	-2.2
美磊 Maglayer__XYplane--V	Vertical	2480	222.4	-10.4	-16.2

XZ Plane Pattern

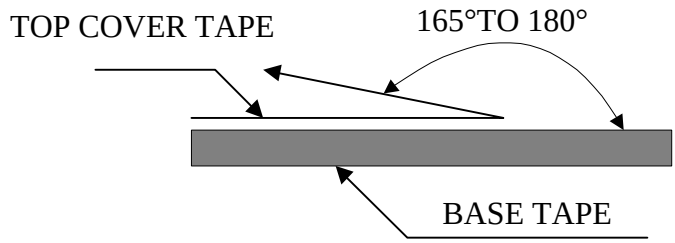


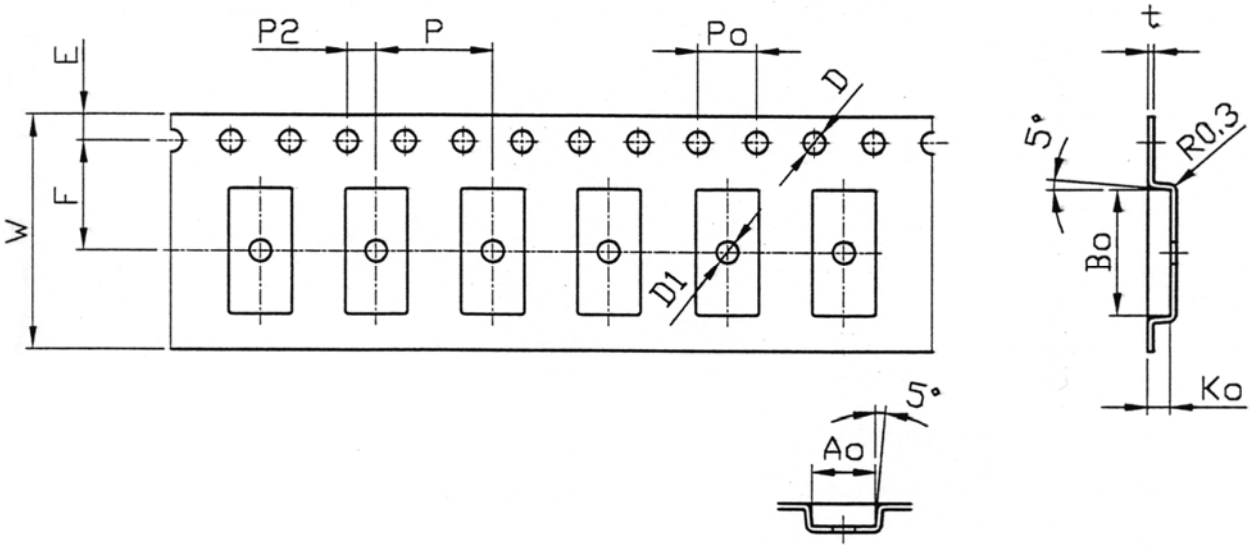
Model No.	Ant. Polarization	Freq(MHz)	Peak angle	Value	Average
美磊 Maglayer__XZplane--H	Horizontal	2480	269.5	-4.7	-9.5
美磊 Maglayer__XZplane--V	Vertical	2480	247.7	2.3	-0.1

PACKAGING FOR SMC



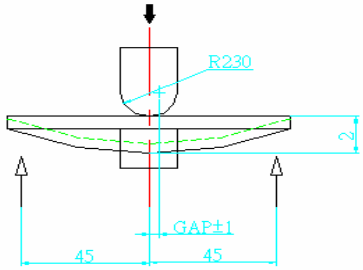
The force for tearing off cover tape is 10 grams in the arrow direction.





Dimensions					
W	16.00	±0.30	**Ao**	2.80	+0.10/-0.00
P	8.00	±0.10	**Bo**	6.00	+0.10/-0.00
E	1.75	±0.10	**Ko**	1.35	±0.10
F	7.50	±0.10	**t**	0.35	±0.05
P2	2.00	±0.10			
D	1.50	+0.10/-0.00			
D1	1.50	+0.25/-0.00			
Po	4.00	±0.20			

MULTILAYER CHIP BEADS RELIABILITY TEST

Heat proof	+85℃ for 24hour	1. No apparent damage 2. Fulfill the electrical spec. after test
Cold proof	-40℃ for 24hour	1. No apparent damage 2. Fulfill the electrical spec. after test
Heat shock	-40~+85℃ for 5cycles each cycle being 30min	1. No apparent damage 2. Fulfill the electrical spec. after test
Moisture proof	+40℃±2, 90~95% R.H. for 96hours	No apparent damage Fulfill the electrical spec. after test
Vibration	10~55Hz vibration frequency with 1.5mm amplitude for two hours in x, y, z directions (10MHz/min)	No apparent damage
Drop shock	Dropped onto hard wood from 50cm height three times in x, y, z directions. The terminals shall be protected.	No apparent damage
Solder heat shock	It shall be possible to hot air re-flow the module twice with a temperature profile shown below.	No apparent damage
Bending test	Solder specimen LTCC components on the test printed circuit board (L:100 x W:40 x T:1.6mm) in appended recommended PCB pattern. Apply the load in direction of the arrow until bending reaches 2mm.  Unit : mm	No apparent damage
Solderability	The dipped surface of the terminal shall be at least 75% covered with solder after dipped in solder bath of 230℃±5 for 5sec. ±1. Remark solder: H63A (Entectic Solder) Remark flux: Resin	
Storage temp & humidity range	Storage temp: < 40℃ Humidity range: < 70%RH	